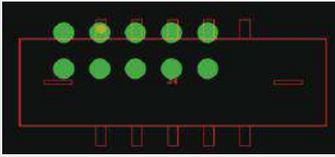
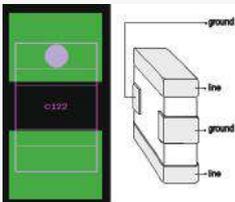
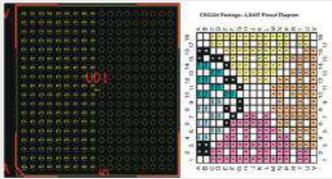
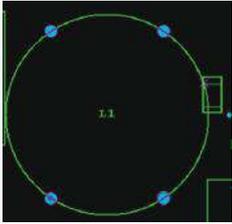
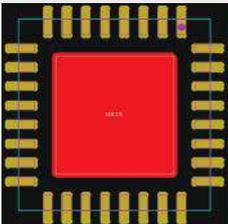
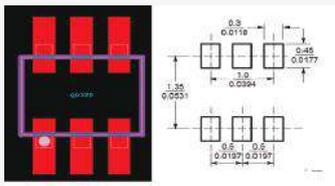
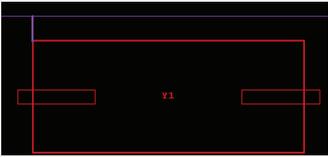
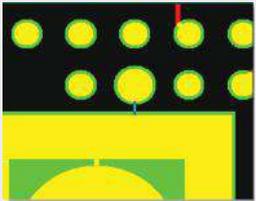
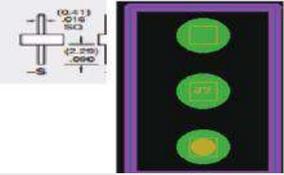
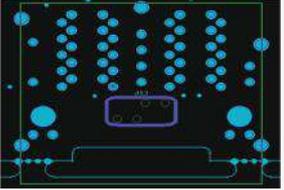
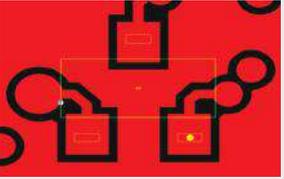
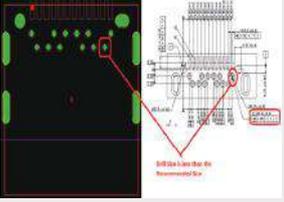
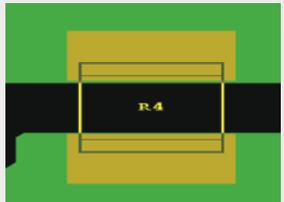
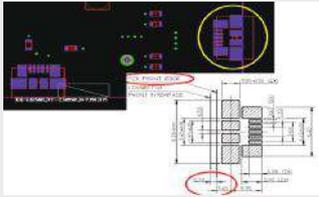
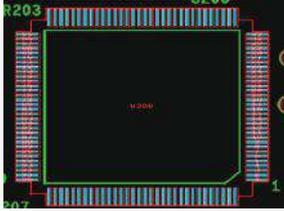
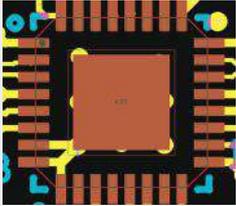
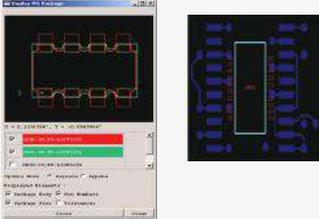
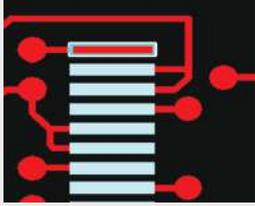
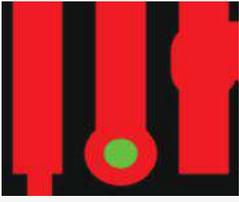


ID	ISSUES-CATEGORY	PRIORITY	IMAGE	OBSERVATIONS	STATUS	CUSTOMER FEEDBACK
1	PACKAGE MISMATCH	CRITICAL		AS PER PART NO IT IS SMD CONNECTOR , IN BOARD WE OBSERVED THROUGH HOLE CONNECTOR. KINDLY CHECK AND UPDATE	OPEN	
2	PIN COUNT MISMATCH	CRITICAL		AS PER PART NO COMPONENT IS HAVING 3 PIN. IN FOOTPRINT GROUND PAD IS MISSED. KINDLY CHECK AND UPDATE	OPEN	
3	PIN 1 MARKING MISMATCH	CRITICAL		PIN 1 MARKING FOR THE FOOTPRINT NOT MATCHING WITH THE DATASHEET. KINDLY CHECK	OPEN	
4	COMPONENTS OVERLAPPING	CRITICAL		COMPONENTS ARE OVERLAPPING MAINTAIN 20 MIL SPACING BETWEEN COMPONENT TO COMPONENT.	OPEN	
5	SOLDER PASTE	CRITICAL		SOLDER PASTE IS MISSED FOR THERMAL PAD KINDLY CHECK AND UPDATE	OPEN	
6	PIN TO PAD MISMATCH	HOT		PAD LENGTH IS TOO BIG, KINDLY MODIFY THE FP AS PER DATA SHEET. BIGGER PADS CAN CREATE SOLDER BALLS/MISALIGNMENT IN ASSEMBLY.	OPEN	
7	COMPONENT TO CONVEYED EDGE SPACING	WARM		COMP TO CONVEYED EDGE SPACING IS 41 MIL FOUND AT Y1. MAINTAIN 125 MIL SPACING FROM CONVEYED EDGE OR PROVIDE HANDLING AREA.	OPEN	
8	TESTPOINTS TOO CLOSE TO EXPOSED COPPER	CRITICAL		TESTPOINTS TOO CLOSE TO EXPOSED COPPER MAY CAUSE ERRORS AT TEST, KINDLY CHECK	OPEN	

ID	ISSUES-CATEGORY	PRIORITY	IMAGE	OBSERVATIONS	STATUS	CUSTOMER FEEDBACK
9	PIN TAIL LENGTH	CRITICAL	 The image shows a technical drawing of a component pin tail on the left and a photograph of the physical component on the right. The pin tail length is highlighted in green in both.	PIN TAIL LENGTH IS 2.29MM AND BOARD THICKNESS IS 1.78MM. PIN PROJECTION IS ONLY 0.5MM. THAT IS NOT SUFFICIENT FOR SOLDERING CONFIRM ONCE.	OPEN	
10	MISSING HOLES	CRITICAL	 A top-down view of a PCB layout with several circular holes highlighted in blue. Some holes are missing or incorrectly placed.	PIN COUNT MISMATCH OBSERVED IN THE DESIGN KINDLY CHECK, COMPONENT CAN NOT BE MOUNTED.	OPEN	
11	TEST POINTS	CRITICAL	 A top-down view of a PCB layout with several test points highlighted in red. Some test points are covered by components.	TESTPOINTS CANNOT BE COVERED BY COMPONENTS, KINDLY CHECK	OPEN	
12	DIFFERENT TRACE WIDTHS CONNECTING PADS	HOT	 A close-up photograph of a component pad on a PCB. The pad is highlighted in blue, and the traces connecting it are highlighted in red. The traces have different widths.	DIFFERENT TRACE WIDTHS CONNECTING PADS / SMALL PIN AREA - PAD AREA MAX- CAN CAUSE TOMBSTONING, KINDLY CHECK	OPEN	
13	SILK SCREEN CLEANUP	HOT	 A photograph of a PCB silk screen with several areas highlighted in red. The text 'TP36' and 'P44' are visible, along with some illegible characters.	SILK SCREEN CLEAN UP IS NOT PROPER KINDLY CHECK.	OPEN	
14	COMPONENTS WITH MISPLACED REFERENCE	CRITICAL	 A top-down view of a PCB layout with several components highlighted in red. The reference designators are C154, C153, R136, R137, C152, and 5.	COMPONENTS WITH MISPLACED REFERENCE DESIGNATORS ON THE SILKSCREEN CAN CAUSE ERRORS AT RE-WORK	OPEN	
15	DRILL SIZE MISMATCH	CRITICAL	 A top-down view of a PCB layout with several holes highlighted in red. A technical drawing of a hole is shown on the right, with a red circle around the drill size specification.	AS PER DATASHEET RECOMMENDED DRILL SIZE IS 0.4MM WHERE AS IN BOARD IT IS 0.3MM.PLEASE VERIFY THE FOOTPRINT	OPEN	
16	COPPER CONNETION	HOT	 A close-up photograph of a component pad on a PCB. The pad is highlighted in green, and the copper connection is highlighted in red. The text 'R.4' is visible.	SMD PADS ARE DIRECTLY CONNECTED TO COPPER, KINDLY CONNECT WITH THERMALS SPOKESTO GET BETTER SOLDERABILITY	OPEN	

ID	ISSUES-CATEGORY	PRIORITY	IMAGE	OBSERVATIONS	STATUS	CUSTOMER FEEDBACK
17	PLACEMENT ISSUE	CRITICAL		AS PER DATA SHEET PLACEMENT OF THE CONNECTOR FROM BOARD EDGE IS 1.45MM ,BUT IN DESIGN WE OBSERVED 2.38MM AT J7 .J7 AND J8 BOTH ARE SAME CONNECTORS BUT PLACED DIFFERENTLY.	OPEN	
18	FINE PITCH COMPONENT	HOT		KINDLY PROVIDE LOCAL FIDUCIALS FOR FINE PITCH COMPONENTS IT WILL HELP DURING ASSEMBLY.	OPEN	
19	LARGE PIN AREA	HOT		LARGE PIN AREA / PAD AREA MAX - LEADS TO POOR SOLDERING (POOR CONNECTIVITY)	OPEN	
20	BOM/AVL VALIDATION	CRITICAL		FIND DISCREPANCIES BETWEEN CAD BOM AND MANUFACTURING BOM IDENTIFY ALTERNATE SUPPLIER FORM AND FIT ISSUES	OPEN	
21	SOLDER PASTE	CRITICAL		MISSING SOLDERPASTE MAY RESULT IN BROKEN NET CONNECTIVITY.KINDLY CHECK ANED UPDATE	OPEN	
22	VIAS DRILLED THROUGH SMD	CRITICAL		VIAS DRILLED THROUGH SMD PADS CAN CAUSE SOLDERING PROCESS RELATED ISSUES, KINDLY CHECK.	OPEN	